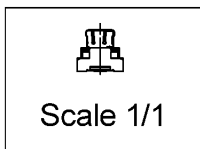
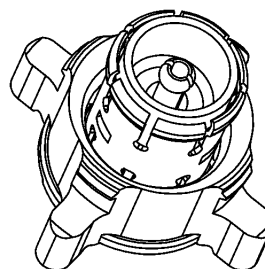
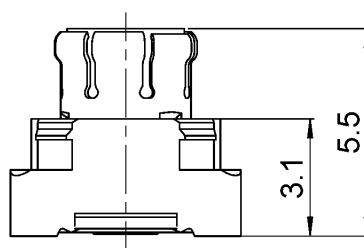
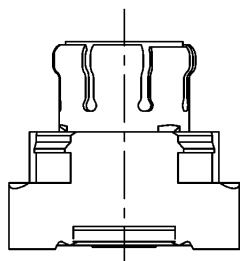
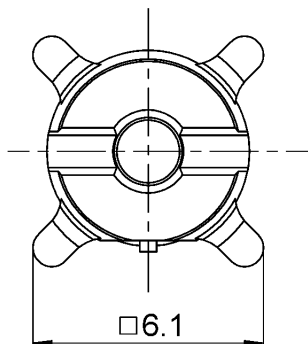
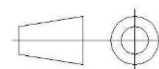


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All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	BERYLLIUM COPPER; BRASS	NPGR
Center contact	BERYLLIUM COPPER; BRASS	NPGR
Outer contact	-	
Insulator	PTFE,LCP	
Gasket		
Others parts		
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
100	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-12.4	GHz
VSWR	1.065	+	0.0000 x F(GHz) Maxi
Insertion loss		0.12	\sqrt{F} (GHz) dB Maxi
RF leakage	- (100	- F(GHz)) dB Maxi
Voltage rating		330	Veff Maxi
Dielectric withstanding voltage		1000	Veff mini
Insulation resistance		1000	M Ω mini

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		10	N mini
Axial force – Opposite end		10	N mini
Torque		NA	N.cm mini
Recommended torque			
Mating		NA	N.cm
Panel nut		NA	N.cm
Mating life		100	Cycles mini
Weight		0.3960	g

ENVIRONMENTAL

Operating temperature	-55/+155	$^{\circ}\text{C}$
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

OTHER CHARACTERISTICS

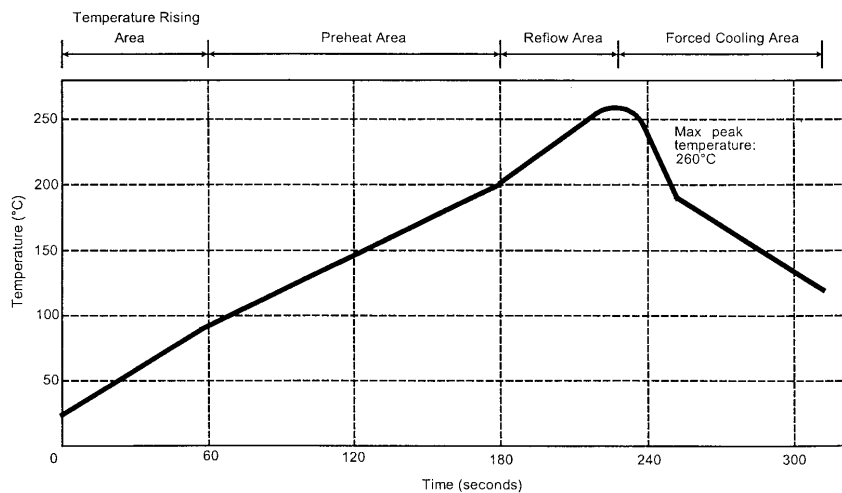
Assembly instruction:

Others:
to 2GHz (1.106 --- 2 to 6GHz)
Interface MMBX only ,up to 2.5GHz
PCB to PCB -45 dB up to 2.5 GHz

SOLDER PROCEDURE OF MMBX RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
A video camera is recommended for positioning of the component.
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven.
Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE

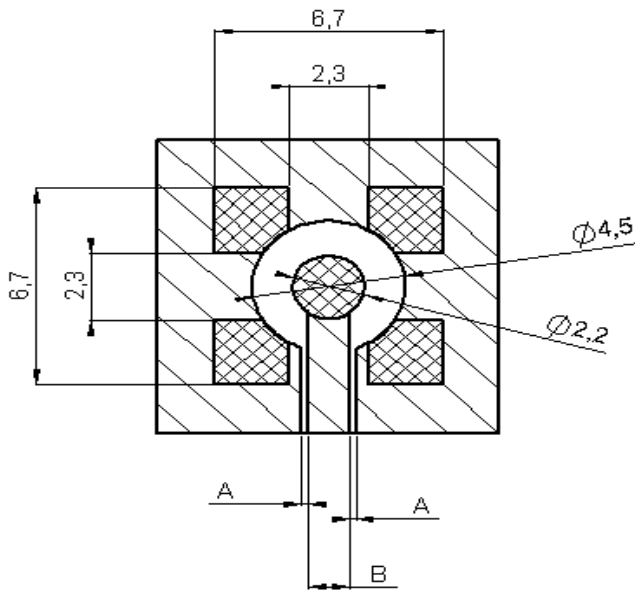


Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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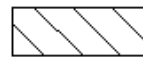
MMBX SERIES INFORMATIONS

PCB



COPLANAR LINE

Pattern and signal are on the same side
The material of PCB is epoxy resin (FR4).
(Er = 4.6)
The solder resist should be printed
Except for the land pattern on the PCB



Pattern



Land for solder paste

APPLICATION 75Ω

WITH B = 0,55mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

APPLICATION 50Ω

WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1,6	0,210

MMBX SERIES INFORMATIONS

